

Descripción del producto

La pasta BEST-solder (Tin) es la mejor opción para reballing IC.

MEJOR marca original,

Calidad verificada

Aplicación: se puede utilizar para laptop / computadora / teléfono móvil / electrodomésticos SMD IC y reparación de BGA IC, herramientas para nivel de chipreparando y línea de fabricación electrónica.

Parámetros tecnológicos

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Temperatura de refrigeración: **ORDESTE**

SOLDER PASTE

Lead-free High temperature



500g

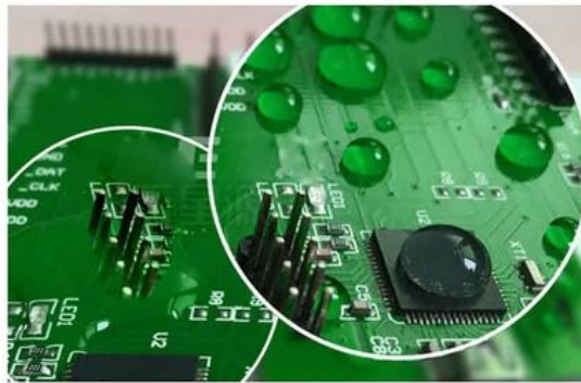
Low residue / Rapid welding / lead free / Solder spot bright / Ag

Product Usage

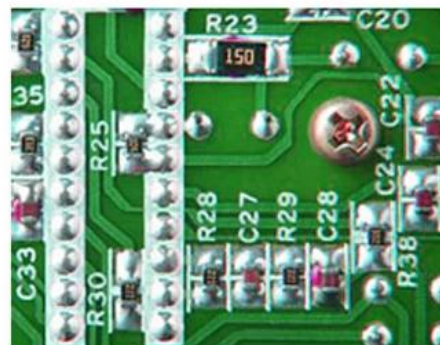
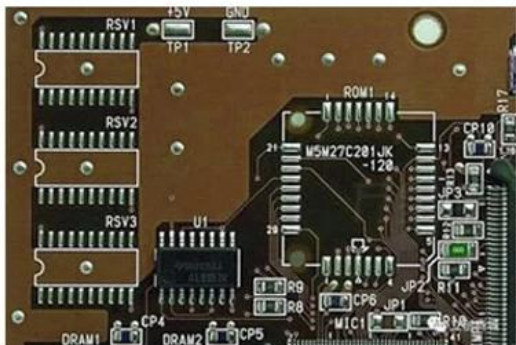


MODEL	BST-705
SHELF LIFE	6 months
INGREDIENT	Sn99/Ag0.3/Cu0.7
WEIGHT	500g
MELTING POINT	217°C

Having a large insulation resistance does not corrode the PCB, and the requirements for no-cleaning can be achieved.



High impedance, full and bright solder, low residue

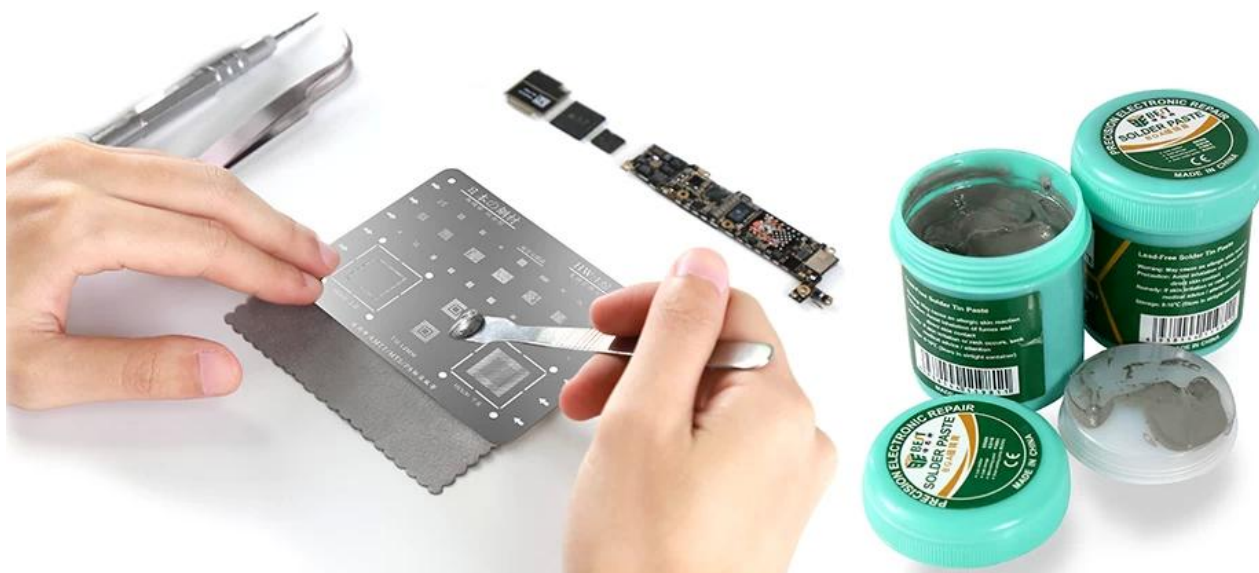


Welding requirements for a wide range of products



TESTING EFFECT

UNIFORM SOLDER JOINT
MEDIUM TEMPERATURE MELTING POINT



PRODUCT SIZE



63.0MM



75MM

52MM

